

Serial No. 10/072,743

Amendments to the Title

Please replace the title with the following:

RADIUSED LEADFRAME METHOD OF FABRICATING AN INTEGRATED CIRCUIT
PACKAGE

Amendments to the Specification:

Please replace the first full paragraph on page 2 with the following:

This application is a continuation of application Serial No. 09/004,214, filed January 9, 1998, pending, now US Patent No. 6,362,426 issued March 26, 2002.

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